KS54AHCT KS74AHCT 845/846

8-Bit Bus Interface D-Type Latches with 3-State Outputs

T-46-07-05

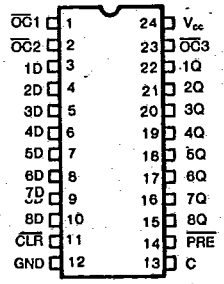
Preliminary Specifications

FEATURE

- 3-state buffer-type outputs drive bus-lines directly
- Bus-structured pinout
- Provides extra bus driving latches necessary for wider address/data paths or buses with parity
- Low power consumption characteristic of CMOS devices
- 3-state outputs with high drive current (I_{OL}=24mA @ V_{OL}=0.5V) for direct bus interface
- Direct interface capability with TTL, NMOS and CMOS devices
- Wide operating volage range: 4.5V to 5.5V
- Characterized for operation over industrial and military temperature ranges:
  KS74AHCT: −40°C to +85°C
  KS54AHCT: −55°C to 125°C
- Package options include plastic "small outline" packages, standard plastic and ceramic 300-mil DIPs

PIN CONFIGURATIONS

'845



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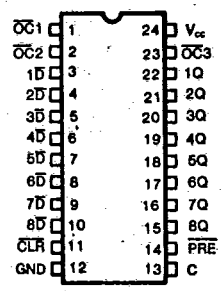

DESCRIPTION

These 8-bit latches feature three-state outputs designed specifically for driving highly capacitive or relatively low impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight latches are transparent D-type. The '845 has noninverting data(D) inputs. The '846 has inverting D inputs. Since $\overline{CLR}$ and $\overline{PRE}$ are independent of the clock, taking the $\overline{CLR}$ input low will cause the eight Q outputs to go low. Taking the $\overline{PRE}$ input low will cause the eight Q outputs to go high. When both $\overline{PRE}$ and $\overline{CLR}$ are taken low, the outputs will follow the preset condition.

The buffered output control inputs ($\overline{OC}1$, $\overline{OC}2$, and $\overline{OC}3$) can be used to place the eight outputs in either a normal logic state (high or low levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impendance state and increased drive provide the capability to drive the bus lines in a bus-organized system without need for interface or pull-up components. The output controls do not affect the internal operation of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

These devices provide speeds and drive capability equivalent to their ALSTTL counterparts and yet maintain CMOS power levels. The input and output voltage levels allow direct interface with TTL, NMOS and CMOS devices without any external components.

All inputs and outputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

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FUNCTION TABLE

'845

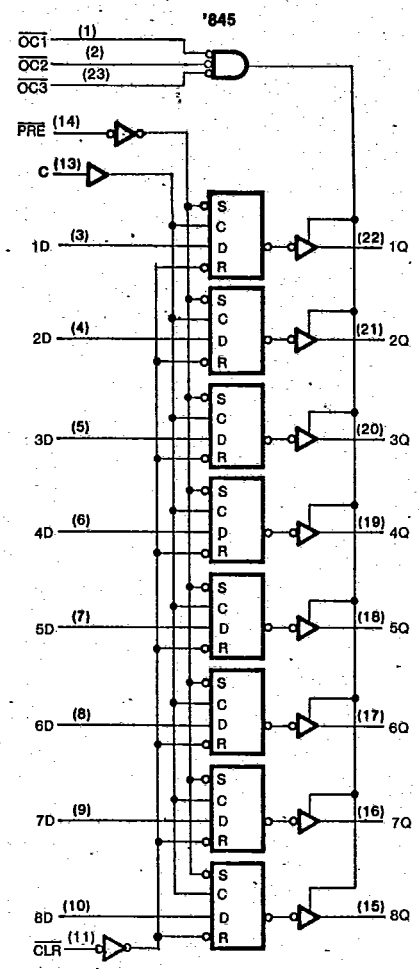
INPUTS							OUTPUT
$\overline{PRE}$	$\overline{CLR}$	$\overline{OC1}$	$\overline{OC2}$	$\overline{OC3}$	C	D	Q
L	H	L	L	L	X	X	H
H	L	L	L	L	X	X	L
L	L	L	L	L	X	X	H
H	H	L	L	L	H	L	L
H	H	L	L	L	H	H	H
H	H	L	L	L	L	X	Q_0
X	X	X	X	H	X	X	Z
X	X	X	H	X	X	X	Z
X	X	H	X	X	X	X	Z

'846

INPUTS							OUTPUT
$\overline{PRE}$	$\overline{CLR}$	$\overline{OC1}$	$\overline{OC2}$	$\overline{OC3}$	C	$\overline{D}$	Q
L	H	L	L	L	X	X	H
H	L	L	L	L	X	X	L
L	L	L	L	L	X	X	H
H	H	L	L	L	H	L	H
H	H	L	L	L	H	H	L
H	H	L	L	L	L	X	Q_0
X	X	X	X	H	X	X	Z
X	X	X	X	H	X	X	Z
X	X	H	X	X	X	X	Z

LOGIC DIAGRAMS

'845



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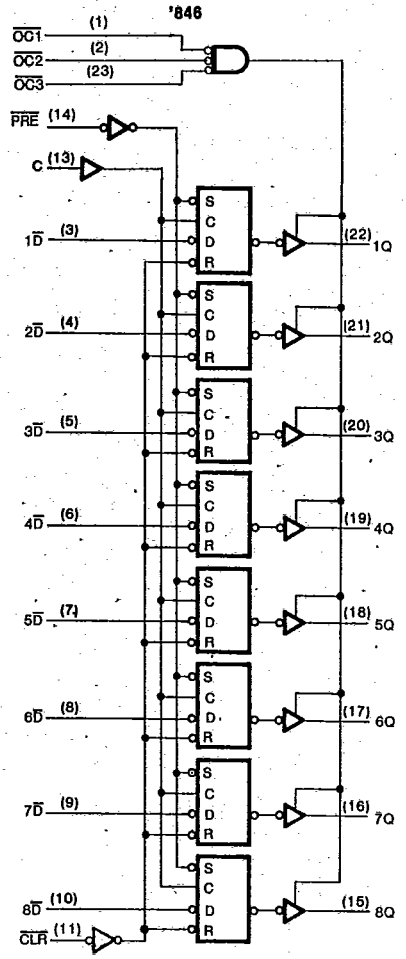

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8-Bit Bus Interface D-Type Latches with 3-State Outputs

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Absolute Maximum Ratings*

Supply Voltage Range V_{CC} . . . . . −0.5V to +7V
DC Input Diode Current, I_{IK}
($V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$) . . . . . ±20 mA
DC Output Diode Current, I_{OK}
($V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$) . . . . ±20 mA
Continuous Output Current Per Pin, I_O
($-0.5V < V_O < V_{CC} + 0.5V$) . . . . . ±70 mA
Continuous Current Through
V_{CC} or GND pins . . . . . ±250 mA
Storage Temperature Range, T_{stg} . . . −65°C to +150°C
Power Dissipation Per Package, P_d† . . . . . 500 mW

* Absolute Maximum Ratings are those values beyond which permanent damage to the device may occur. These are stress ratings only and functional operation of the device at or beyond them is not implied. Long exposure to these conditions may affect device reliability.

† Power Dissipation temperature derating:
Plastic Package (N): −12mW/°C from 65°C to 85°C
Ceramic Package (J): −12mW/°C from 100°C to 125°C

Recommended Operating Conditions

Supply Voltage, V_{CC} . . . . . 4.5V to 5.5V
DC Input & Output Voltages*, V_{IN}, V_{OUT} . . 0V to V_{CC}
Operating Temperature
Range KS74AHCT: −40°C to +85°C
KS54AHCT: −55°C to +125°C
Input Rise & Fall Times, t_r, t_f . . . . . Max 500 ns

* Unused inputs must always be tied to an appropriate logic voltage level (either V_{CC} or GND)

DC ELECTRICAL CHARACTERISTICS (V_{CC}=5V±10% Unless Otherwise Specified)

Characteristic	Symbol	Test Conditions	T_a=25°C	KS74AHCT T_a=−40°C to +85°C	KS54AHCT T_a=−55°C to +125°C	Unit
			Typ	Guaranteed Limits		
Minimum High-Level Input Voltage	V_{IH}			2.0	2.0	2.0	V
Maximum Low-Level Input Voltage	V_{IL}			0.8	0.8	0.8	V
Minimum High-Level Output Voltage	V_{OH}	V_{IN}=V_{IH} or V_{IL} I_O=−20μA I_O=−4mA	V_{CC} 4.2	V_{CC} −0.1 3.98	V_{CC} −0.1 3.84	V_{CC} −0.1 3.7	V
Maximum Low-Level Output Voltage	V_{OL}	V_{IN}=V_{IH} or V_{IL} I_O=20μA I_O=4mA I_O=8mA	0	0.1 0.26 0.39	0.1 0.33 0.5	0.1 0.4	V
Maximum Input Current	I_{IN}	V_{IN}=V_{CC} or GND		±0.1	±1.0	±1.0	μA
Maximum Quiescent Supply Current	I_{CC}	V_{IN}=V_{CC} or GND I_{OUT}=0μA		8.0	80.0	160.0	μA
Additional Worst Case Supply Current	ΔI_{CC}	per input in V_I=2.4V other Inputs: at V_{CC} or GND I_{OUT}=0μA		2.7	2.9	3.0	mA

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AC ELECTRICAL CHARACTERISTICS (Input t_r, $t_f \leq 2$ ns), AHCT845

Characteristic	Symbol	Conditions†	$T_a = 25°C$ $V_{CC} = 5.0V$	KS74AHCT $T_a = -40°C$ to $+85°C$ $V_{CC} = 5.0V \pm 10\%$		KS54AHCT $T_a = -55°C$ to $+125°C$ $V_{CC} = 5.0V \pm 10\%$		Unit
			Typ	Min	Max	Min	Max	
Propagation Delay Clk to Q	t_{PLH}		13		22		26	ns
	t_{PHL}		13		22		26	
Propagation Delay D to Q	t_{PLH}		8		15		20	ns
	t_{PHL}		8		15		20	
Propagation Delay $\overline{CLR}$ to Q	t_{PLH}		16		26		31	ns
	t_{PHL}		16		26		31	
Propagation Delay $\overline{PRE}$ to Q	t_{PLH}		16		26		31	ns
	t_{PHL}		16		26		31	
Propagation Delay $\overline{OC}$ to Q	t_{PZH}		12		20		24	ns
	t_{PZL}		12		20		24	
Propagation Delay $\overline{OC}$ to Q	t_{PHZ}		12		20		24	ns
	t_{PLZ}		12		20		24	
Input Capacitance	C_{IN}		5					pF
Power dissipation Capacitance*	C_{PD}							pF

* C_{PD} determines the no-load dynamic power dissipation: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$.
† For AC switching test circuits and timing waveforms see section 2.

AC ELECTRICAL CHARACTERISTICS (Input t_r, $t_f \leq 2$ ns), AHCT846

Characteristic	Symbol	Conditions†	$T_a = 25°C$ $V_{CC} = 5.0V$	KS74AHCT $T_a = -40°C$ to $+85°C$ $V_{CC} = 5.0V \pm 10\%$		KS54AHCT $T_a = -55°C$ to $+125°C$ $V_{CC} = 5.0V \pm 10\%$		Unit
			Typ	Min	Max	Min	Max	
Propagation Delay Clk to Q	t_{PLH}		14		24		32	ns
	t_{PHL}		14		24		32	
Propagation Delay $\overline{D}$ to Q	t_{PLH}		10		17		22	ns
	t_{PHL}		10		17		22	
Propagation Delay $\overline{CLR}$ to Q	t_{PLH}		13		22		26	ns
	t_{PHL}		13		22		26	
Propagation Delay $\overline{PRE}$ to Q	t_{PLH}		13		22		26	ns
	t_{PHL}		13		22		26	
Propagation Delay $\overline{OC}$ to Q	t_{PZH}		12		20		24	ns
	t_{PZL}		12		20		24	
Propagation Delay $\overline{OC}$ to Q	t_{PHZ}		12		20		24	ns
	t_{PLZ}		12		20		24	
Input Capacitance	C_{IN}		5					pF
Power dissipation Capacitance*	C_{PD}							pF

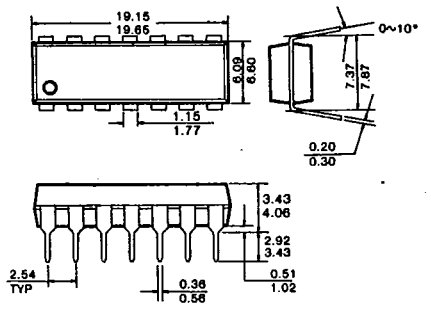
* C_{PD} determines the no-load dynamic power dissipation: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$.
† For AC switching test circuits and timing waveforms see section 2.

PACKAGE DIMENSIONS

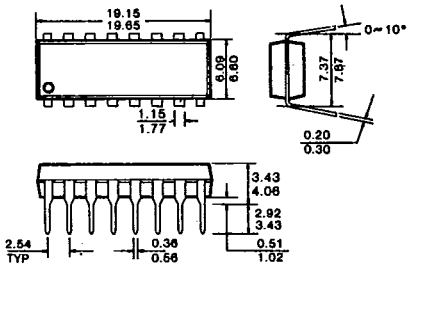
T-90-20

1. PLASTIC PACKAGES

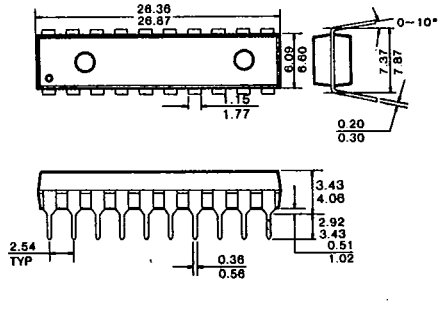
14-Pin Plastic DIP **Units: mm**



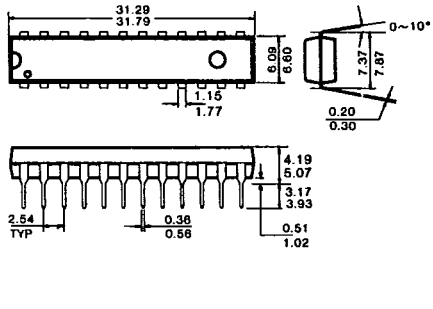
16-Pin Plastic DIP **Units: mm**



20-Pin Plastic DIP **Units: mm**



24-Pin Plastic DIP **Units: mm**



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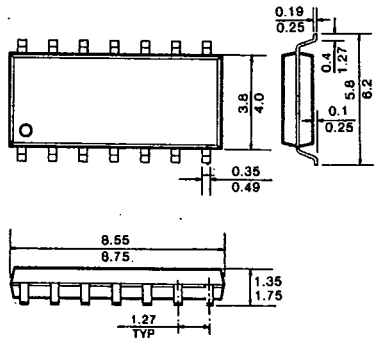
PACKAGE DIMENSIONS

T-90-20

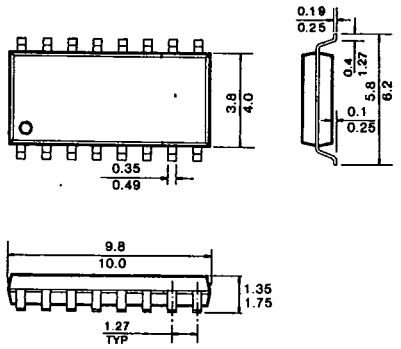
14-Pin SOP

Unit: mm



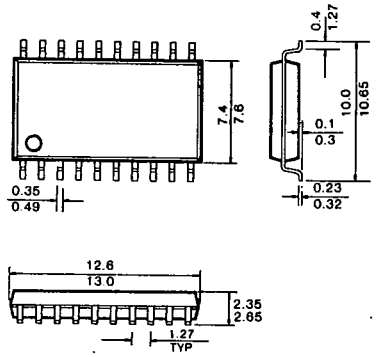
16-Pin SOP

Unit: mm



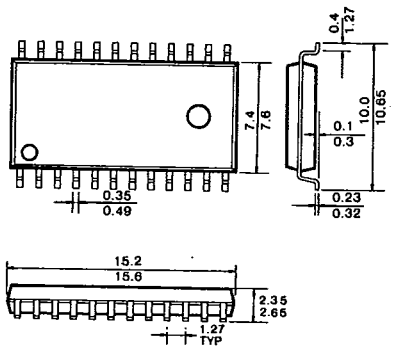
20-Pin SOP

Unit: mm



24-Pin SOP

Unit: mm

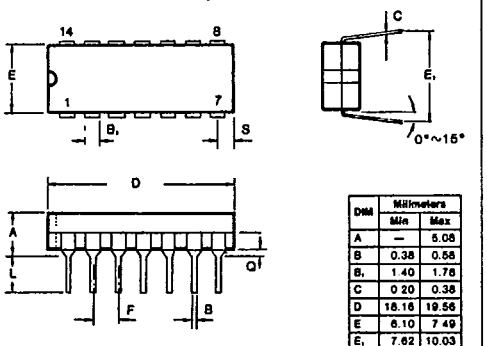


PACKAGE DIMENSIONS

T-90-20

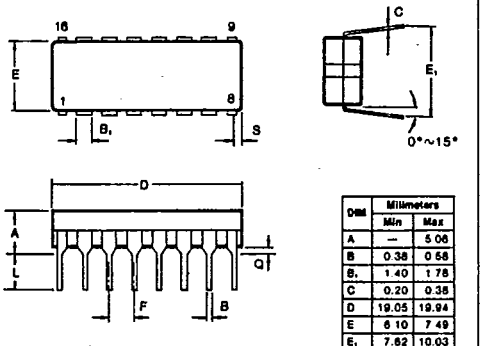
2. CERAMIC PACKAGES

14-Pin Ceramic DIP Units: mm



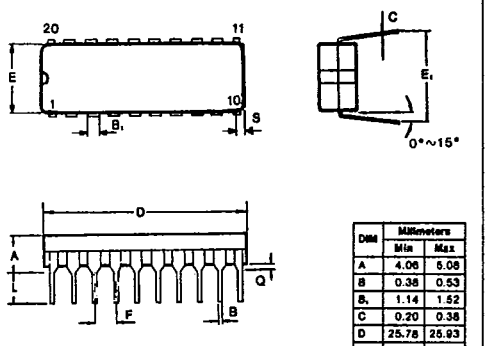
DIM	Millimeters	
	Min	Max
A	—	5.08
B	0.38	0.58
B1	1.40	1.78
C	0.20	0.38
D	18.16	19.56
E	6.10	7.49
E1	7.62	10.03
F	2.54	
L	3.18	4.19
Q	0.51	1.02
S	1.91	2.29

16-Pin Ceramic DIP Units: mm



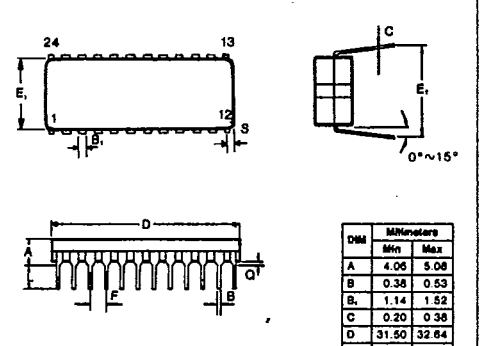
DIM	Millimeters	
	Min	Max
A	—	5.08
B	0.38	0.58
B1	1.40	1.78
C	0.20	0.38
D	19.05	19.94
E	6.10	7.49
E1	7.62	10.03
F	2.54	
L	3.18	4.19
Q	0.51	1.02
S	0.51	1.14

20-Pin Ceramic DIP Units: mm



DIM	Millimeters	
	Min	Max
A	4.06	5.08
B	0.38	0.53
B1	1.14	1.52
C	0.20	0.38
D	25.78	25.93
E	6.10	6.60
E1	7.77	7.98
F	2.54	
L	3.73	4.01
Q	0.38	0.89
S	0.51	1.14

24-Pin Ceramic DIP Units: mm



DIM	Millimeters	
	Min	Max
A	4.06	5.08
B	0.38	0.53
B1	1.14	1.52
C	0.20	0.38
D	31.50	32.64
E	7.24	7.75
E1	7.77	7.98
F	2.54	
L	3.73	4.01
Q	0.508	1.778
S	1.65	1.93

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